

## The RF Line

### NPN SILICON RF POWER TRANSISTOR

... designed primarily for driver applications in 12.5 volt single-sideband amplifiers from 2.0 to 30 MHz.

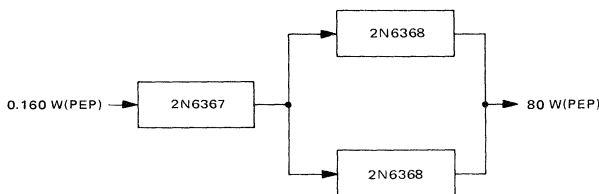
- Optimized for Operation from a 12.5 Volt Supply
- Power Output @ 12.5 Vdc, 30 MHz — 9.0 W (PEP)
- Intermodulation Distortion at Rated Power Output — IMD = -30 dB (Max)

#### \*MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector-Emitter Voltage	V <sub>CEO</sub>	18	Vdc
Collector-Base Voltage	V <sub>CBO</sub>	36	Vdc
Emitter-Base Voltage	V <sub>EBO</sub>	4.0	Vdc
Collector Current — Continuous	I <sub>C</sub>	2.0	Adc
Total Device Dissipation @ T <sub>C</sub> = 25°C Derate above 25°C	P <sub>D</sub>	20 0.114	Watts W/°C
Storage Temperature Range	T <sub>stg</sub>	-65 to +200	°C

\*Indicates JEDEC Registered Data.

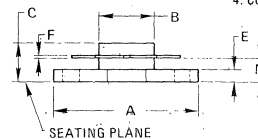
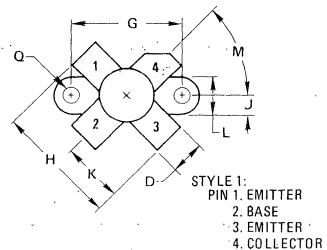
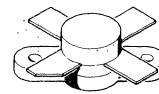
#### TYPICAL DRIVER APPLICATION 2-30 MHz WIDE BAND AMPLIFIER



9 W (PEP) — 30 MHz

RF POWER  
TRANSISTOR

NPN SILICON



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	24.64	24.89	0.970	0.980
B	9.47	9.73	0.373	0.383
C	6.07	7.14	0.239	0.281
D	5.59	5.84	0.220	0.230
E	2.16	2.67	0.085	0.105
F	0.10	0.15	0.004	0.006
G	18.29	18.54	0.720	0.730
H	21.59	22.10	0.850	0.870
J	3.12	3.23	0.123	0.127
K	10.80	11.05	0.425	0.435
L	6.22	6.48	0.245	0.255
M	40°	50°	40°	50°
N	3.81	4.57	0.150	0.180
Q	2.97	3.12	0.117	0.123

CASE 211-01

**\*ELECTRICAL CHARACTERISTICS** ( $T_C = 25^\circ\text{C}$  unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
<b>OFF CHARACTERISTICS</b>				
Collector-Emitter Breakdown Voltage ( $I_C = 50 \text{ mA dc}, I_B = 0$ )	$BV_{CEO}$	18	—	Vdc
Collector-Emitter Breakdown Voltage ( $I_C = 50 \text{ mA dc}, V_{BE} = 0$ )	$BV_{CES}$	36	—	Vdc
Emitter-Base Breakdown Voltage ( $I_E = 5.0 \text{ mA dc}, I_C = 0$ )	$BV_{EBO}$	4.0	—	Vdc
Collector Cutoff Current ( $V_{CE} = 15 \text{ Vdc}, V_{BE} = 0, T_C = 55^\circ\text{C}$ )	$I_{CES}$	—	10	mA dc
<b>ON CHARACTERISTICS</b>				
DC Current Gain ( $I_C = 500 \text{ mA dc}, V_{CE} = 5.0 \text{ Vdc}$ )	$h_{FE}$	5.0	50	—
<b>DYNAMIC CHARACTERISTICS</b>				
Current-Gain – Bandwidth Product ( $I_C = 500 \text{ mA dc}, V_{CE} = 12.5 \text{ Vdc}, f = 50 \text{ MHz}$ )	$f_T$	50	—	MHz
Output Capacitance ( $V_{CB} = 12.5 \text{ Vdc}, I_E = 0, f = 1.0 \text{ MHz}$ )	$C_{ob}$	—	90	pF
<b>FUNCTIONAL TESTS</b>				
Common-Emitter Amplifier Power Gain ( $V_{CC} = 12.5 \text{ Vdc}, P_{out} = 9.0 \text{ W(PEP)}, I_{C(max)} = 1.0 \text{ A dc}, f_1 = 30 \text{ MHz}, f_2 = 30.001 \text{ MHz}$ )	$G_{PE}$	14	—	dB
Collector Efficiency ( $V_{CC} = 12.5 \text{ Vdc}, P_{out} = 9.0 \text{ W(PEP)}, I_{C(max)} = 1.0 \text{ A dc}, f_1 = 30 \text{ MHz}, f_2 = 30.001 \text{ MHz}$ )	$\eta$	36	—	%
Intermodulation Distortion ( $V_{CC} = 12.5 \text{ Vdc}, P_{out} = 9.0 \text{ W(PEP)}, I_{C(max)} = 1.0 \text{ A dc}, f_1 = 30 \text{ MHz}, f_2 = 30.001 \text{ MHz}$ )	IMD	—	-30	dB

\*Indicates JEDEC Registered Data

**FIGURE 1 – 30 MHz TEST CIRCUIT**

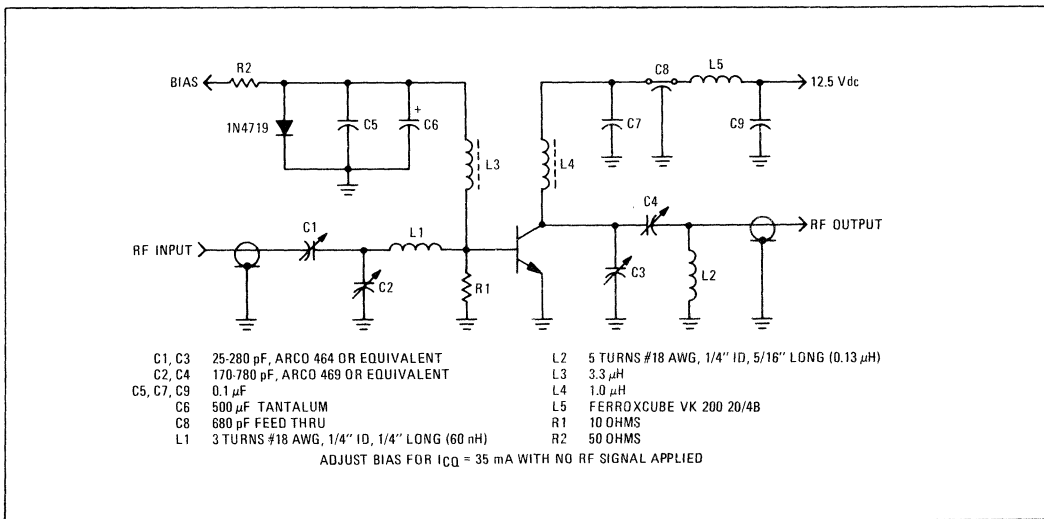


FIGURE 2 – LINEAR OUTPUT POWER versus FREQUENCY

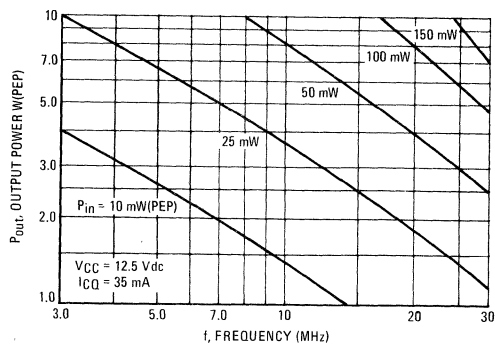


FIGURE 3 – OUTPUT POWER versus INPUT POWER

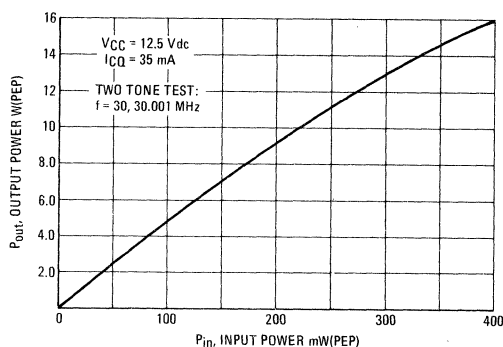


FIGURE 4 – OUTPUT POWER versus INPUT POWER

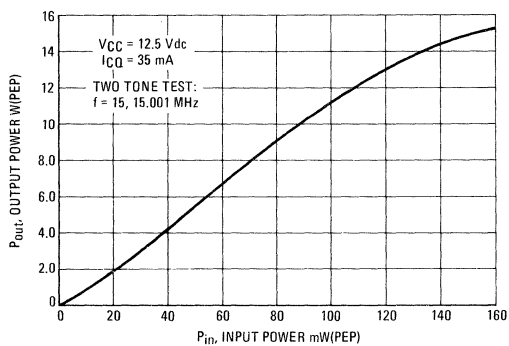


FIGURE 5 – OUTPUT POWER versus INPUT POWER

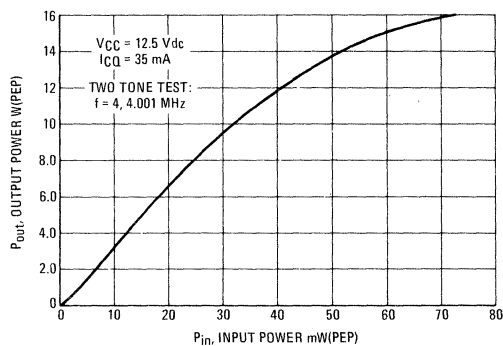


FIGURE 6 – INTERMODULATION DISTORTION versus OUTPUT POWER

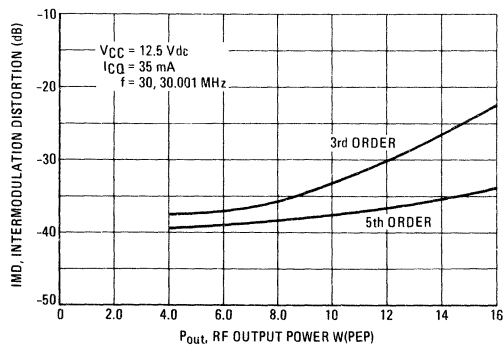


FIGURE 7 – LINEAR OUTPUT POWER versus SUPPLY VOLTAGE

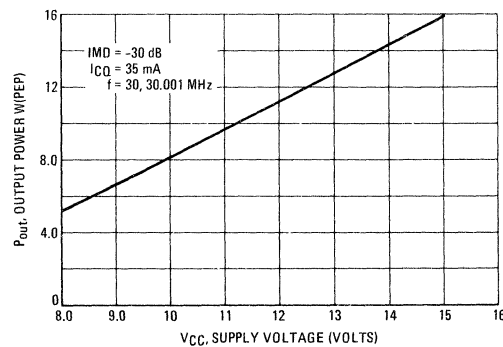


FIGURE 8 – PARALLEL EQUIVALENT INPUT RESISTANCE

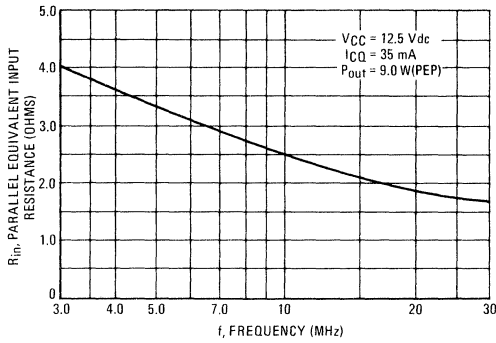


FIGURE 9 – PARALLEL EQUIVALENT INPUT CAPACITANCE

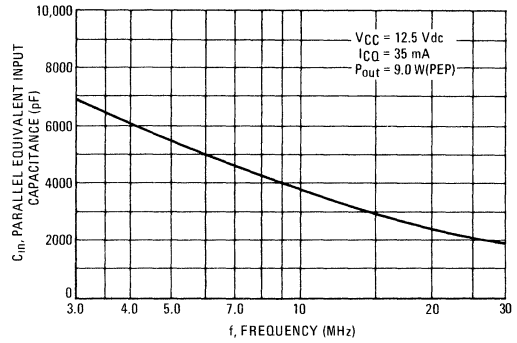


FIGURE 10 – PARALLEL EQUIVALENT OUTPUT RESISTANCE

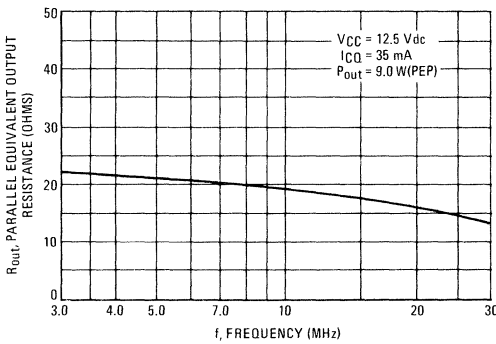


FIGURE 11 – PARALLEL EQUIVALENT OUTPUT CAPACITANCE

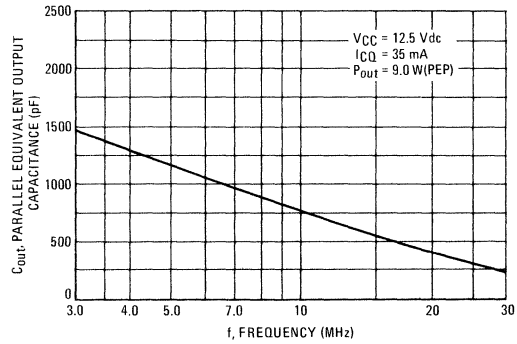


FIGURE 12 – CURRENT-GAIN – BANDWIDTH PRODUCT

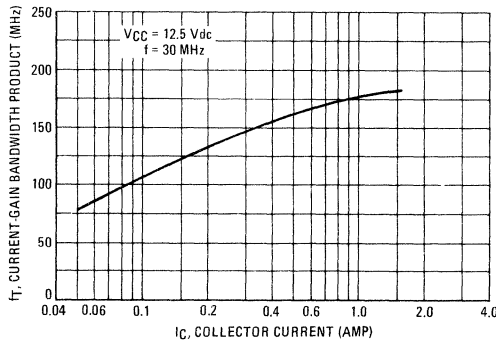


FIGURE 13 – COLLECTOR CURRENT versus BASE-EMITTER VOLTAGE

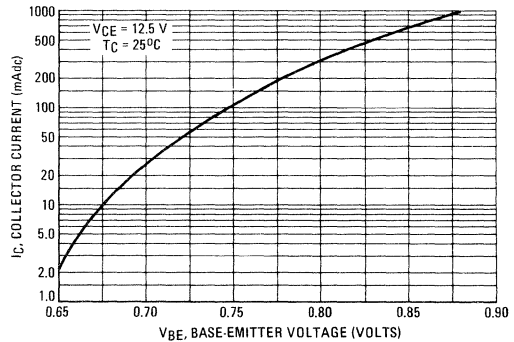


FIGURE 14 – OUTPUT CAPACITANCE

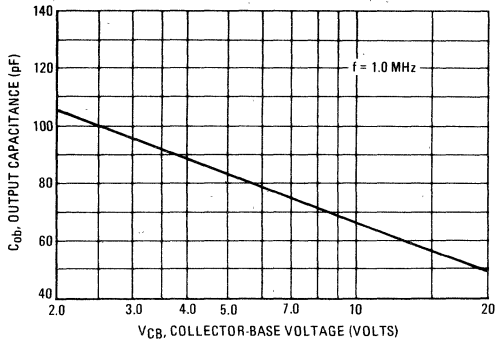


FIGURE 15 – INPUT CAPACITANCE

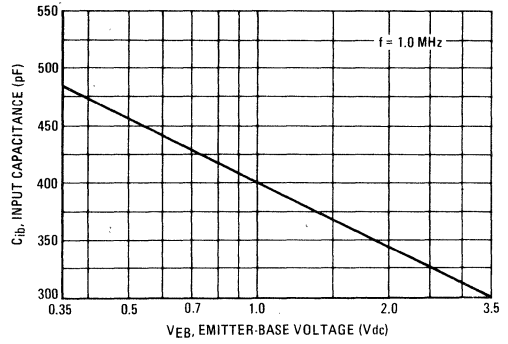


FIGURE 16 – DC SAFE OPERATING AREA

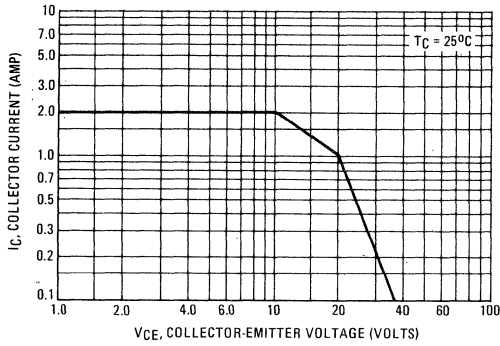


FIGURE 17 – RF POWER DISSIPATION

